

## Descriptions

The RLCS822 is a bidirectional low-power dual port, high-speed, USB 2.0 analog switch with integrated protection for USB Type-C™ systems. The device is configured as a dual 4:1 or 1:4 switch. It is optimized for use with the USB 2.0 DP/DM lines in a USB Type-C™ system.

The RLCS822 has low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480Mbps). Each switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. Its bandwidth is wide enough to pass high-speed USB 2.0 differential signals (480 Mb/s) with good signal integrity. The RLCS822 contains special circuitry on the COM+/- pins which allows the device to withstand a VBUS short to USB 2.0 DP/DM lines when the USB devices are either powered off or powered on. The AS3USB4000Q integrated over-voltage protection on the COM+/- pins can withstand up to DC 30V with automatic shutoff circuitry in order to protect system components behind the switch.

GPIO controls of S1/2 and \_EN are 1.8V logic compatible. The RLCS822 is available in QFN 2.5x3.4-24L with Pb-free and Halogen-free making it a perfect candidate for mobile and space constrained applications.

## Features

- Supply Range 2.5 V to 5.5 V
- Differential 4:1 or 1:4 Switch/Multiplexer
- Up to DC 30V Overvoltage Protection (OVP) on COM+/- Ports
- IEC 64000-4-5 Surge Protection w/o External TVS onto COM+/- Ports:  $\pm 30V$
- Powered Off Protection When VDD = 0 V
- Low RON of 10  $\Omega$  Typical
- Insertion loss: -1dB@200MHz, -2dB@650MHz, -3dB@1GHz
- CON of 4.8 pF, 1.8-V Compatible Logic Inputs
- Standard Temperature Range of 0°C to 85°C

## Applications

- Anywhere a USB Type-C™ or Micro-B Connector is Used
- Mobile Phones,
- Tablets and
- Notebooks

## Typical Application

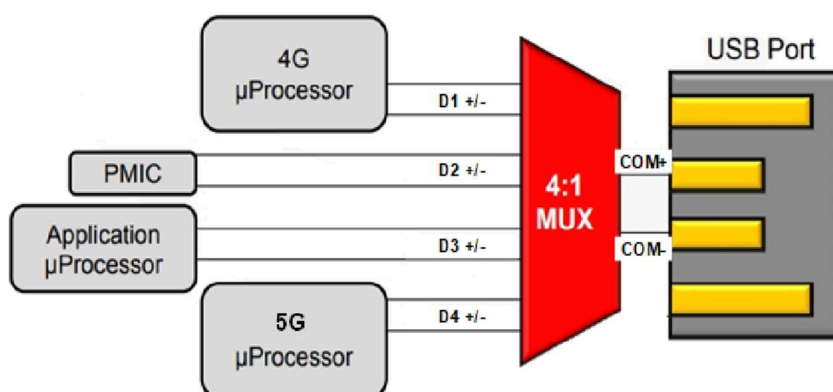


Fig.1 Typical Application

## Functional Diagram

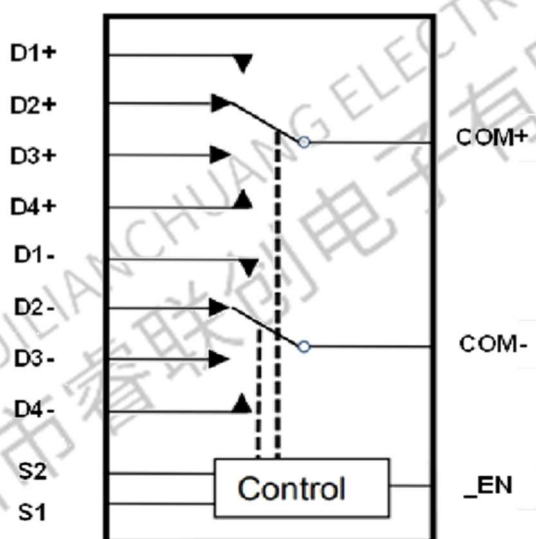


Fig.2 Functional Diagram

## Order Information

Package		Part Number	Quantity per Reel
QFN 2.5 x 3.4 -24L	Tape and Reel	RLCS822QN24	3000PCS

## Pin Configuration

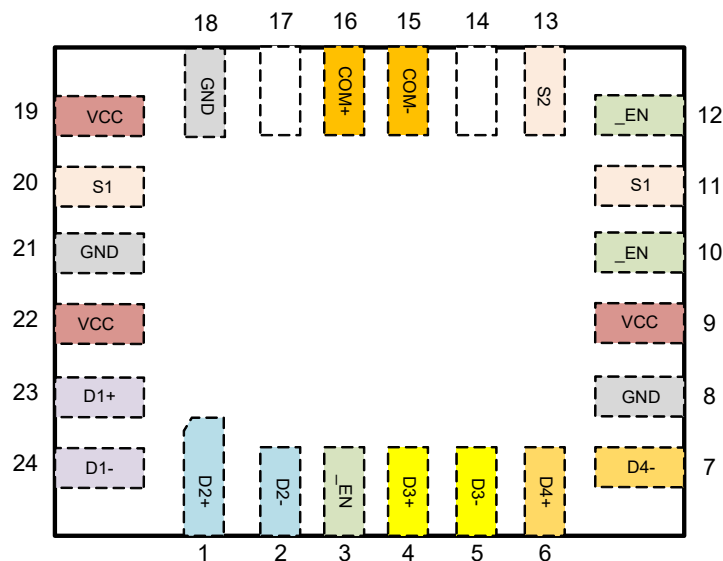


Fig.3 QFN 2.5 x 3.4 -24L

## Pin Descriptions

QFN2.5x3.4-24L	Pin Name	Signal Type	Description
1	D2+	I/O	Signal I/O, Channle 2
2	D2-	I/O	Signal I/O, Channle 2
3,10,12	_EN	I	Chip Enable, Active Low
4	D3+	I/O	Signal I/O, Channle 3
5	D3-	I/O	Signal I/O, Channle 3
6	D4+	I/O	Signal I/O, Channle 4
7	D4-	I/O	Signal I/O, Channle 4
8,18,21	GND	GND	Power Ground
9,19,22	VCC	PWR	Positive Supply Voltage
11,20	S1	I	Channel Select
13	S2	I	Channel Select
14,17	NC	/	Not Connection
15	COM-	I/O	Signal I/O, Common Port
16	COM+	I/O	Signal I/O, Common Port
23	D1+	I/O	Signal I/O, Channle 1
24	D1-	I/O	Signal I/O, Channle 1

Table-1 Pin Descriptions

## Truth Table

Function	S2	S1	_EN
COM+/- to D1+/-	L	L	L
COM+/- to D2+/-	L	H	L
COM+/- to D3+/-	H	L	L
COM+/- to D4+/-	H	H	L
All Switches Hi-Z	X	X	H

Table-2 Truth Table

## Electrical Characteristics (Ta=25°C, VDD=3.3V, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
POWER SUPPLY						
Supply Voltage Range	VDD		2.5	3.3	5.5	V
Supply Current	I <sub>CC</sub>	<sub>EN</sub> =1      switch-off		0.6	2	uA
		<sub>EN</sub> =0      switch-on		33		uA
SEL/ <sub>EN</sub> DIGITAL INPUT CONTROL						
control input logic high	V <sub>IH</sub>		1.6		5.5	V
control input logic low	V <sub>IL</sub>		-0.1		0.5	V
Internal pull-down resistor	R <sub>PD</sub>			2		MΩ
SWITCH ON RESISTANCE AND OFF LEAKAGE						
On-Resistance	R <sub>ON</sub>	V <sub>IS</sub> = 0V~0.4V    I <sub>OUT</sub> =8mA		10	11	Ω
R <sub>ON</sub> Flatness <sup>(1)</sup>	R <sub>FLAT</sub>	V <sub>IS</sub> = 0V~0.4V    I <sub>OUT</sub> =8mA		0.3	0.5	Ω
R <sub>ON</sub> Matching Between Channels <sup>(2)</sup>	ΔR <sub>ON</sub>	V <sub>IS</sub> = 0V~0.4V    I <sub>OUT</sub> =8mA		0.1	0.2	Ω
OFF Leakage Current	I <sub>LEAK</sub>	V <sub>CO+/-</sub> = 10V    V <sub>L1+/-</sub> = V <sub>D2+/-</sub> =0V		31	50	uA
SWITCH DYNAMICS						
On Capacitance	C <sub>ON</sub>	V <sub>CO+/-</sub> = 0.2V, f = 1MHz		4		pF
Off Capacitance	C <sub>OFF</sub>	V <sub>CO+/-</sub> = 0.2V, f = 1MHz		3		pF
Off Isolation	Off	f = 250MHz, R <sub>T</sub> = 50Ω, C <sub>L</sub> = 0pF		-38		dB
Crosstalk <sup>(3)</sup> (Channel-to-Channel)	X <sub>TALK</sub>	f = 250MHz, R <sub>T</sub> = 50Ω, C <sub>L</sub> = 0pF		-41		dB
-3dB Bandwidth	BW	R <sub>T</sub> =50Ω, C <sub>L</sub> =0pF Signal Power 0dBm	0.9	1		GHz
Break-Before-Make	BBM	V <sub>L1+/-</sub> = V <sub>D2+/-</sub> = 0.4V,    R <sub>L</sub> =50Ω		1.5		uS
Turn-on Time	t <sub>OFF</sub>	V <sub>CO+/-</sub> = 0.4V,    R <sub>L</sub> =50Ω <sub>EN</sub> switches from High to Low		20		uS
Turn-off Time	t <sub>OFF</sub>	V <sub>CO+/-</sub> = 0.4V,    R <sub>L</sub> =50Ω <sub>EN</sub> switches from Low to High		1.2		uS
Propagation Delay	t <sub>PD</sub>	V <sub>CO+/-</sub> = 0.4V,    R <sub>L</sub> =50Ω		200		pS

Table-4 Electrical Characteristics

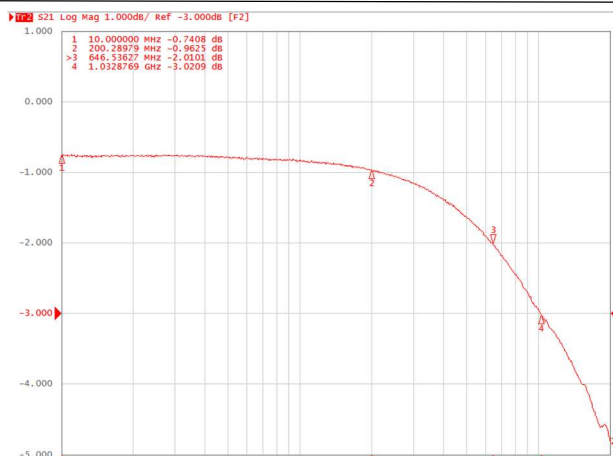
### Note:

(1) Flatness is defined as the difference between maximum and minimum value of ON-resistance at the specified analog signal voltage points.

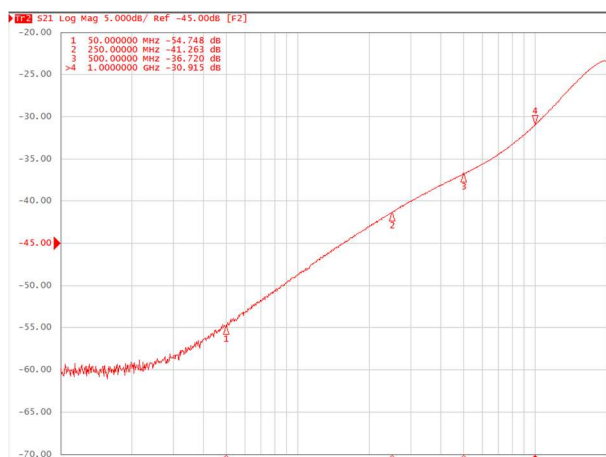
(2) R<sub>ON</sub> matching between channels is calculated by subtracting the channel with the lowest max Ron value from the channel with the highest max Ron value.

(3) Crosstalk is inversely proportional to source impedance

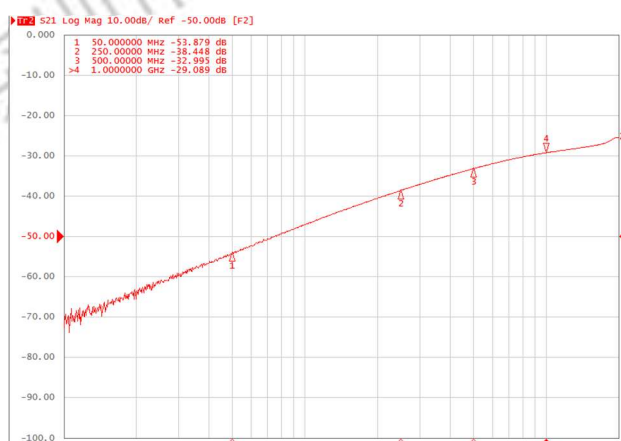
## Typical Performance Curves (Ta=25°C, VDD=3.0V, CAP=0.1uF, unless otherwise noted)



**Fig.1 Switch Bandwidth or Insertion Loss**



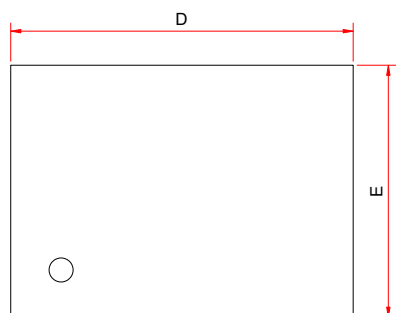
**Fig.2 Switch Channel to Channel Cross-Talk**



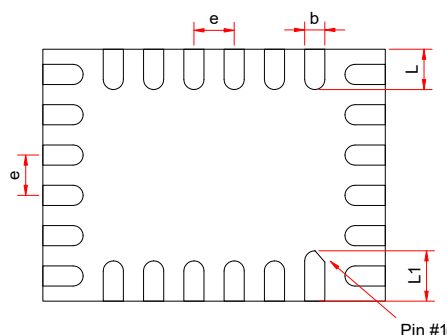
**Fig.3 Switch Off Isolation**

## PACKAGE OUTLINE DIMENSIONS

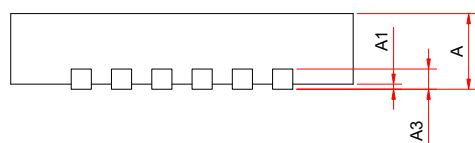
QFN 2.5 x 3.4 -24L



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20Ref		
D	3.35	3.40	3.45
E	2.45	2.50	2.55
L	0.30	0.40	0.50
L1	0.40	0.50	0.60
b	0.15	0.20	0.25
e	0.40BSC		

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